

Amendments to the Specification:

Page 8, amend the paragraph beginning at line 5 to read as follows:

The heat sink 14 used in the invention may be made of any material as long as it has a heat conductivity higher than that of the wiring circuit boards. Metal materials are particularly suitable, as they generally have high heat conductivities. When ceramic substrates are used as the wiring circuit boards 12 and 13, metal composite materials with a low thermal-expansion property may be used in order to ensure good bonding with the wiring circuit boards 12 and 13. Examples of such metal composite materials include a ~~copper-invar-copper~~ copper-INVAR (alloy comprising iron and nickel) - copper three-layer clad material, and a composite material produced by firing copper and copper oxide powders together.